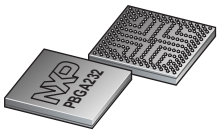
SOT2309-1

PBGA232, plastic ball grid array, 232 terminals, 0.502 mm pitch, 10 mm x 10 mm x 1.33 mm body

13 October 2026 **Package information**

1 Package summary



Terminal position code	Q (quad)
Package type descriptive code	PBGA232
Package style descriptive code	PBGA (plastic ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	30-10-2024
Manufacturer package code	98ASA02288D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	10	-	mm
package width	-	10	-	mm
package height	-	1.33	-	mm
nominal pitch	-	0.502	-	mm
actual quantity of termination	-	232	-	

2 Package outline

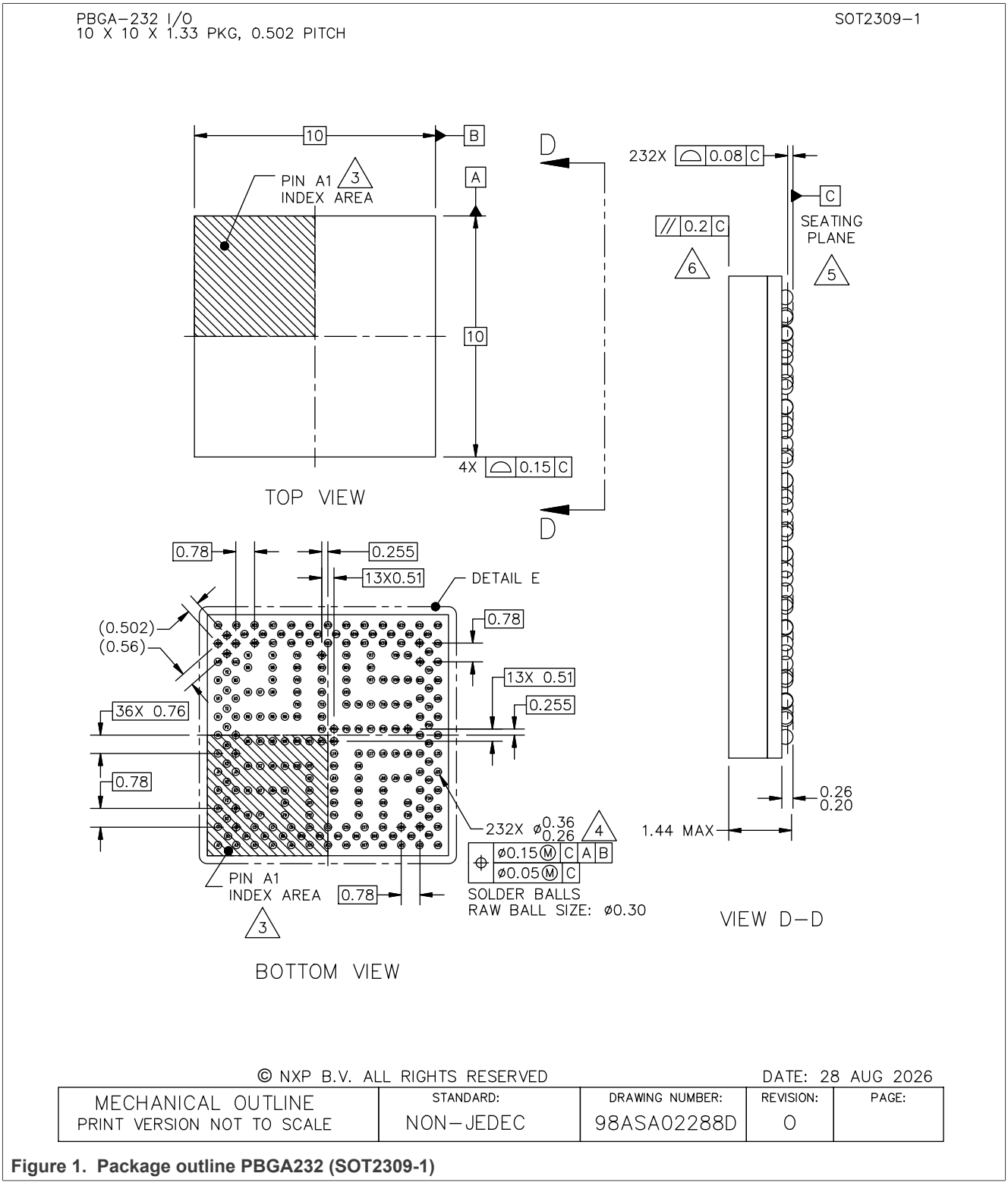


Figure 1. Package outline PBGA232 (SOT2309-1)

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3 Soldering

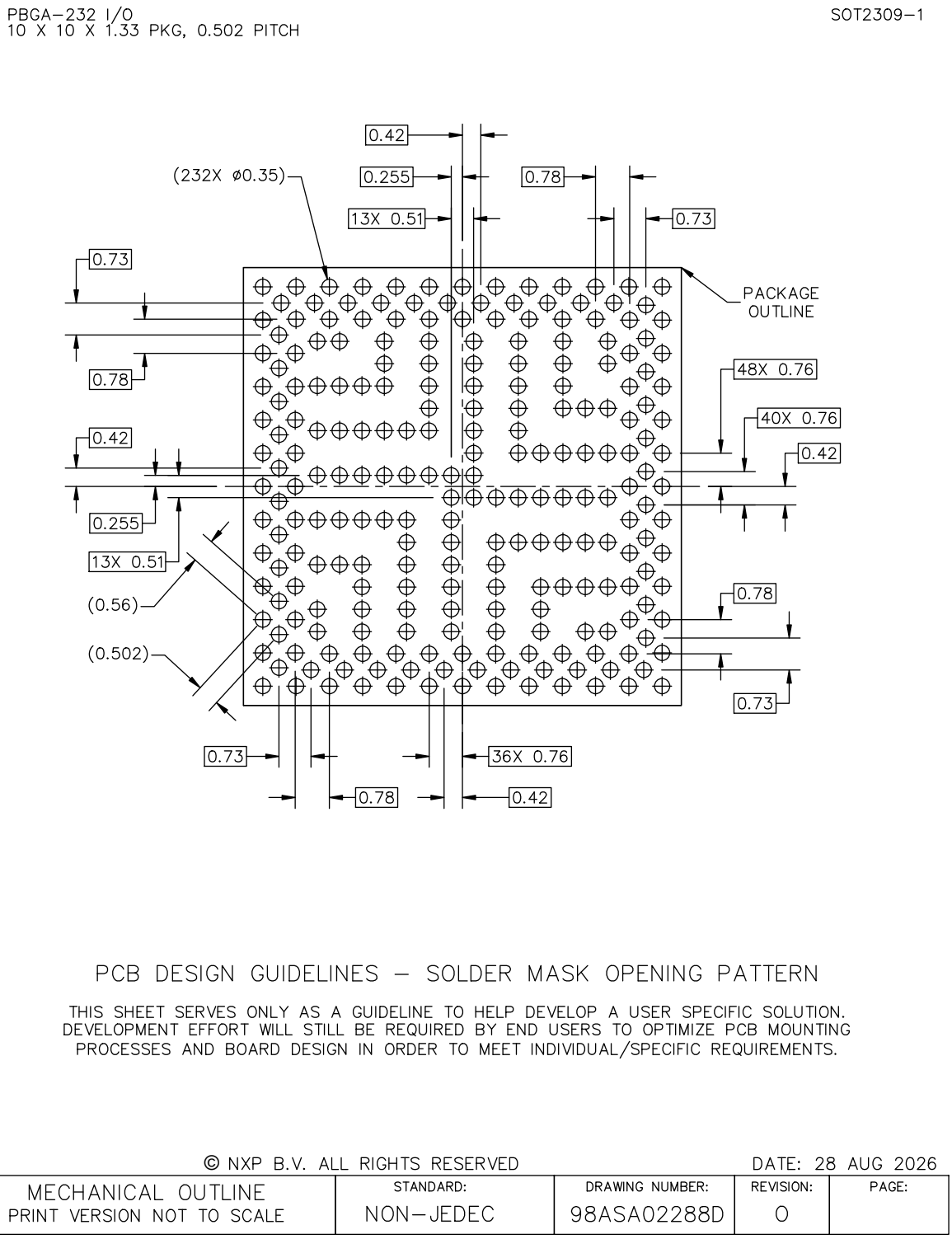

Figure 2. Reflow soldering footprint part1 for PBGA232 (SOT2309-1)

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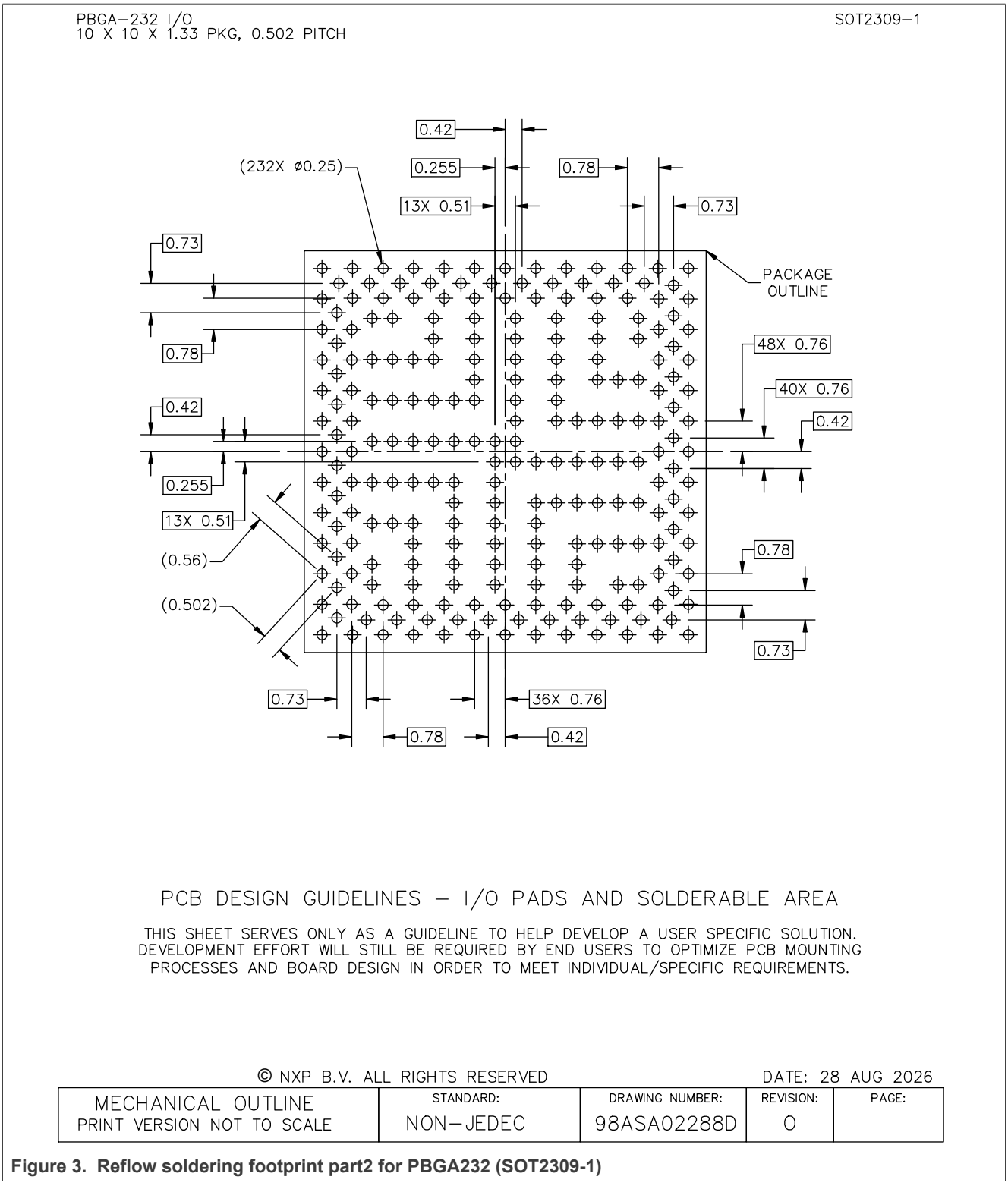

Figure 3. Reflow soldering footprint part2 for PBGA232 (SOT2309-1)

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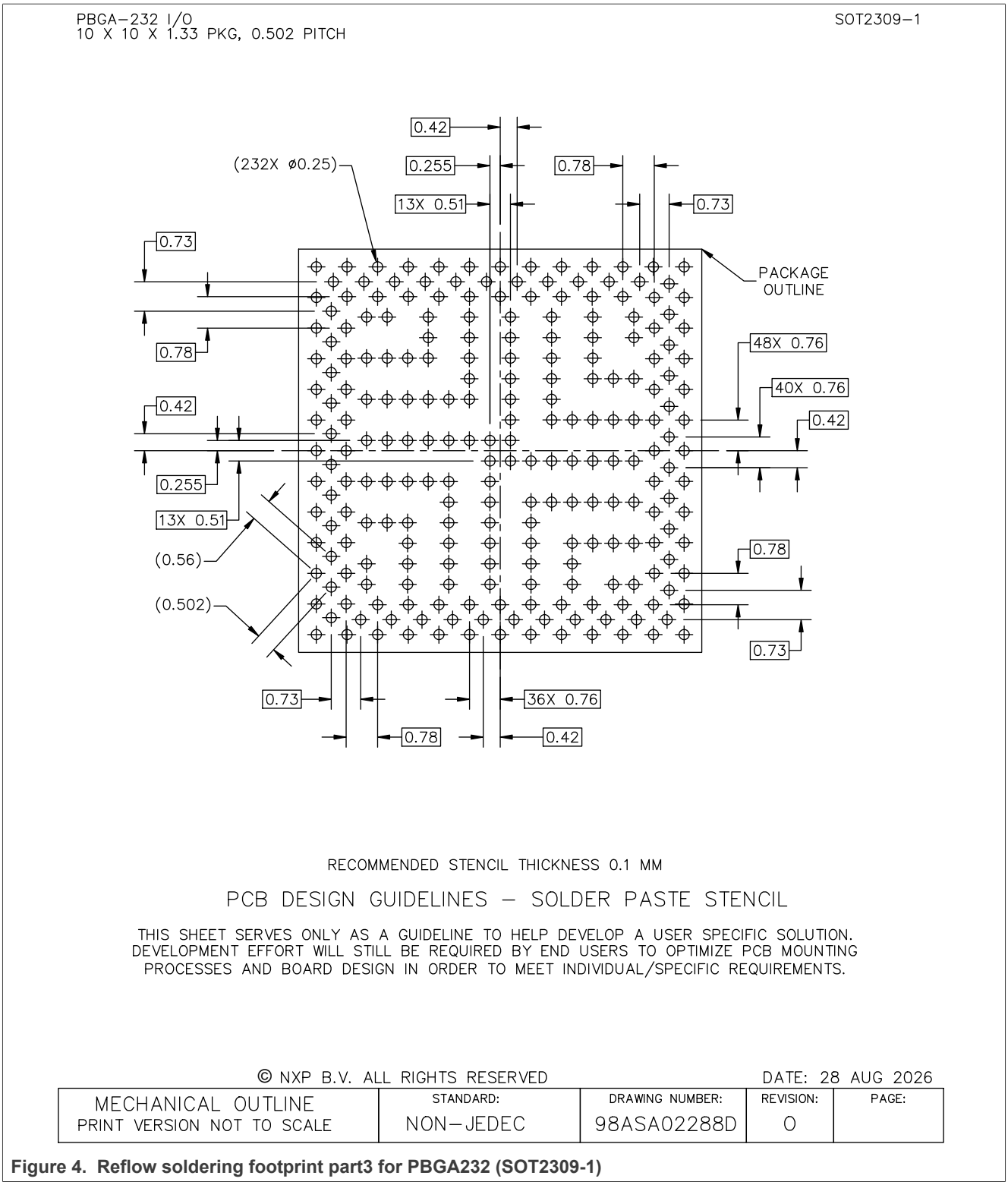

Figure 4. Reflow soldering footprint part3 for PBGA232 (SOT2309-1)

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PBGA232, plastic ball grid array, 232 terminals, 0.502 mm pitch, 10 mm x 10 mm x 1.33 mm body

PBGA−232 I/O
10 X 10 X 1.33 PKG, 0.502 PITCH

SOT2309−1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 28 AUG 2026

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON−JEDEC	DRAWING NUMBER: 98ASA02288D	REVISION: 0	PAGE:

Figure 5. Package outline note PBGA232 (SOT2309-1)

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PBGA232, plastic ball grid array, 232 terminals, 0.502 mm pitch, 10 mm x 10 mm x 1.33 mm body

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